

Bright Copper SLOTOCOUP BC 2610

Strongly acidic copper electrolyte for the deposition of high bright copper layers.

APPLICATION

- Decorative
- Intermediate- and final layer (e.g. POP)
- Electroforming

PROCESS

- Rack plating lines
- Soluble anodes
- Suitable antitarnish process available for this application

BENEFITS

- Excellent bright throwing power
- Excellent levelling
- Easy electrolyte operation
- Suitable Schloetter antitarnish protection Antitarnish ALS 20 available

Bright Copper ACG 8

Bright Copper ACG 8 is an easy to operate electrolyte. The brightness and excellent levelling of the copper layers deposited from this electrolyte as well as the high deposition rate are the features of Bright Copper ACG 8. The copper coatings have low internal stress, are ductile and soft and can be easily polished. Steel parts which have been carefully mechanically prepared can normally be bright nickel- and chrome plated directly after copper-plating without intermediate polishing.

Bright Copper ACG 8 is also suitable for thick copper plating of electroforming. Bright Copper ACG 8 is insensitive to impurities.

Copper SLOTOCOUP PC 81

The Copper SLOTOCOUP PC 81 process gives a fine grained, bright and very ductile deposit. Deposits from Copper SLOTOCOUP PC 81 have very low internal stress and are resistant to thermal shocks.

Copper SLOTOCOUP PC 81 is ideal for the plating of printed circuit boards and electroforming.

The Copper SLOTOCOUP PC 81 process is easy to control as it is maintained with a single additive. There are no detrimental breakdown products formed.

Copper SLOTOCOUP PC 81 is suitable for the deposition of thick copper deposits.